

STL66DN3LLH5

Automotive-grade dual N-channel 30 V, 5.9 mΩ typ., 20 A STripFET™ H5 Power MOSFET in a PowerFLAT™ 5x6 double island package

Datasheet - production data

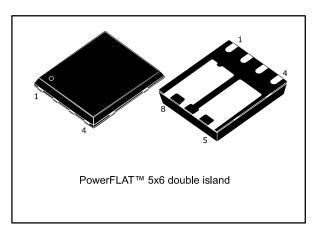
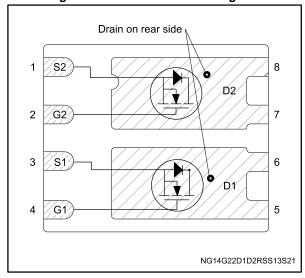


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	ΙD	Ртот
STL66DN3LLH5	30 V	$6.5~\text{m}\Omega$	20 A	4.7 W

- Designed for automotive applications and AEC-Q101 qualified
- Logic level V_{GS(th)}
- 175 °C maximum junction temperature
- Wettable flanks package

Applications

Switching applications

Description

This device is a dual N-channel Power MOSFET developed using STMicroelectronics' STripFET™ H5 technology. The device has been optimized to achieve very low on-state resistance, contributing to a FoM that is among the best in its class.

Table 1: Device summary

Order code	Marking	Package	Packing
STL66DN3LLH5	66DN3LH5	PowerFLAT™ 5x6 double island	Tape and reel

Contents STL66DN3LLH5

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STL66DN3LLH5 Electrical ratings

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{DS}	Drain-source voltage	30	V	
V_{GS}	Gate-source voltage	±22	V	
I _D ⁽¹⁾	Drain current (continuous) at T _{case} = 25 °C	78.5	Δ	
ID(**)	Drain current (continuous) at T _{case} = 100 °C	55.5	А	
l _D ⁽²⁾	Drain current (continuous) at T _{pcb} = 25 °C		Α	
ID(=)	Drain current (continuous) at T _{pcb} = 100 °C	14.2	A	
I _{DM} ⁽²⁾⁽³⁾	Drain current (pulsed)	80	Α	
Ртот	Total dissipation at T _{case} = 25 °C	72	14/	
P _{TOT} ⁽¹⁾	Total dissipation at T _{pcb} = 25 °C	4.7	W	
T _{stg}	T _{stg} Storage temperature			
Tj	T _j Operating junction temperature		°C	

Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case	2.08	°C/W
R _{thj-pcb} ⁽¹⁾	R _{thj-pcb} ⁽¹⁾ Thermal resistance junction-pcb		C/VV

Notes:

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AV}	Avalanche current, not repetitive	18.5	Α
E _{AS} ⁽¹⁾	Single pulse avalanche energy	270	mJ

Notes:

 $^{^{(1)}}$ This value is rated according to $R_{\text{thj-c}}$

 $^{^{(2)}}$ When mounted on a 1-inch² FR-4, 2 Oz copper board, t < 10 s.

⁽³⁾ Pulse width is limited by safe operating area.

 $^{^{(1)}}$ When mounted on a 1-inch² FR-4, 2 Oz copper board, t < 10 s.

 $^{^{(1)}}$ starting $T_j = 25~^{\circ}C,~I_D = 38~A,~V_{DD} = 24~V.$

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 5: Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			>
	Zoro goto voltago drain	$V_{GS} = 0 \text{ V}, V_{DS} = 30 \text{ V}$			1	
IDSS	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 30 V, T _C = 125 °C			100	μΑ
I _{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 22 \text{ V}$			±10	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1		3	V
D	Static drain-source on-	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		5.9	6.5	m0
R _{DS(on)}	resistance	V _{GS} = 4.5 V, I _D = 10 A		7.1	7.9	mΩ

Table 6: Dynamic

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
Ciss	Input capacitance		ı	1500	•	
Coss	Output capacitance	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz},$	-	230	•	pF
C _{rss}	Reverse transfer capacitance	$V_{GS} = 0 V$	1	23	ı	Pi
Q_g	Total gate charge	$V_{DD} = 15 \text{ V}, I_D = 19 \text{ A},$	-	12	•	
Qgs	Gate-source charge	V _{GS} = 4.5 V (see Figure 14: "Test circuit for gate charge	-	5	•	nC
Q_{gd}	Gate-drain charge	behavior")	1	4.4	ı	

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	$V_{DD} = 15 \text{ V}, I_D = 9.5 \text{ A}$	-	8.8	-	
tr	Rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$ (see Figure 13: "Test circuit for	ı	18	ı	
t _{d(off)}	Turn-off delay time	resistive load switching	ı	26	ı	ns
t _f	Fall time	times" and Figure 18: "Switching time waveform")	-	4	-	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		ı		20	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		80	Α
V _{SD} ⁽²⁾	Forward on voltage	V _{GS} = 0 V, I _{SD} = 19 A	ı		1.1	V
t _{rr}	Reverse recovery time	$I_{SD} = 19 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s,}$	ı	24		ns
Qrr	Reverse recovery charge	$V_{DD} = 25 \text{ V}, T_j = 150 \text{ °C (see}$ Figure 15: "Test circuit for	-	12		nC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	1	1.8		А

Notes:

 $^{^{\}left(1\right) }$ Pulse width is limited by safe operating area.

 $^{^{(2)}}$ Pulse test: pulse duration = 300 $\mu s,$ duty cycle 1.5%.

2.1 Electrical characteristics (curves)

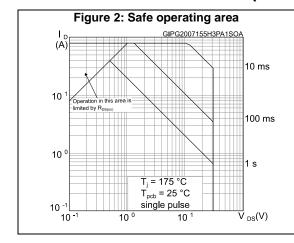


Figure 3: Thermal impedance K GIPG2107155H3PA1ZTH δ = 0.5 δ = 0.02 δ = 0.01 δ = 0.02 δ = 0.05 δ = 0.02 δ = 0.01 δ = 0.02 δ = 0.01 δ = 0.02 δ = 0.05 δ

Figure 4: Output characteristics

(A)

V_{GS} = 6,7,8,9,10 V

120

V_{GS} = 5 V

120

V_{GS} = 4 V

80

V_{GS} = 3 V

N_{DS} (V)

Figure 5: Transfer characteristics

GIPG2007155H3PA1TCH

VDS = 2V

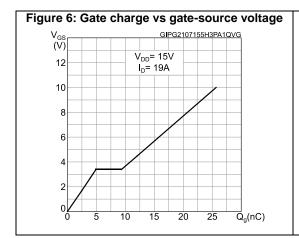
60

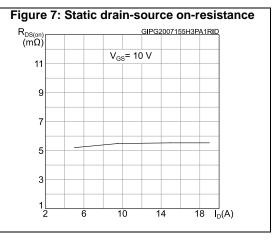
40

20

0

1 2 3 VDS (V)





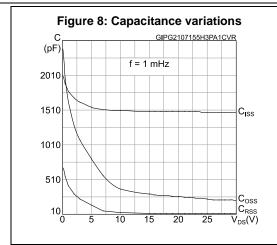


Figure 9: Normalized gate threshold voltage vs temperature

V_{GS(th)} GIPG2007155H3PA1VTH
(norm.)

1.2

1.0

0.8

0.6

0.4

0.2

-75
-25
25
75
125
175 T_j(°C)

Figure 10: Normalized on-resistance vs temperature

R_{DS(on)} GIPG2007155H3PA1RON
(norm.)

1.6

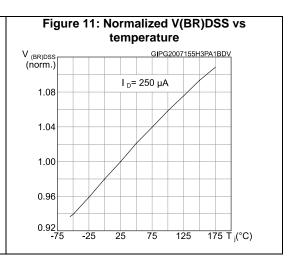
1.2

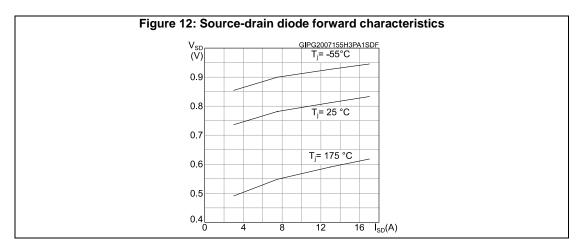
0.8

0.4

0.4

0
-100 -50 0 50 100 150 175 T_j(°C)





Test circuits STL66DN3LLH5

3 Test circuits

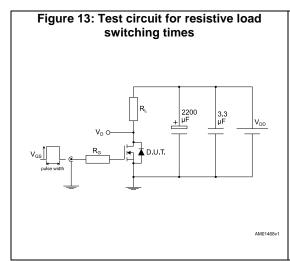
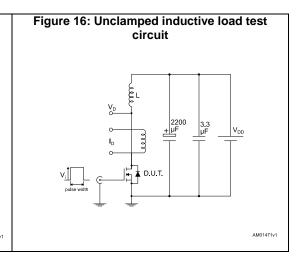


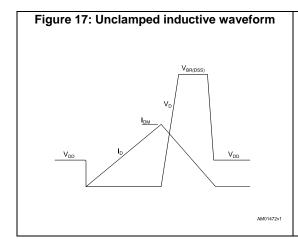
Figure 14: Test circuit for gate charge behavior

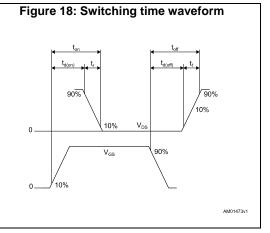
12 V 47 KQ 100 nF D.U.T.

VGS 1 KQ 100 NF D.U.T.

AM01469v1







4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 double island WF type C package information

Figure 19: PowerFLAT™ 5x6 double island WF type C package outline Bottom view Pin 1 identification E7 E6 Detail A Scale 3:1 0.08 b (x8) Side view Top view Detail A identification $\overset{\times}{\infty}$ 826945_DI_WF_typeC_r13

Table 9: PowerFLAT™ 5x6 double island WF type C mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D	5.00	5.20	5.40
D2	1.68		1.88
Е	6.20	6.40	6.60
E2	3.50		3.70
E4	0.55		0.75
E5	0.08		0.28
E6	2.35		2.55
E7	0.40		0.60
е		1.27	
L	0.90		1.10
L1		0.275	
K	1.05		1.35

5.4 4.45 3.15 1.9 0.4 99. 0.65 <u>(x4)</u> 1.25

3.81

Figure 20: PowerFLAT™ 5x6 double island recommended footprint (dimensions are in mm)

8256945_DI_WF_FP_R13

Package information STL66DN3LLH5

4.2 PowerFLAT™ 5x6 WF packing information

Figure 21: PowerFLAT™ 5x6 WF tape

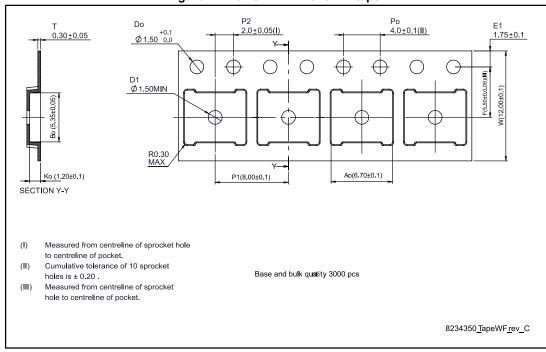
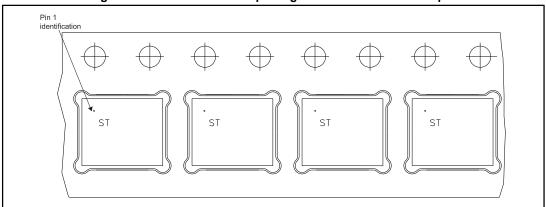


Figure 22: PowerFLAT™ 5x6 package orientation in carrier tape



PART NO.

R25.00

R25.00

R25.00

R25.00

R25.00

R25.00

R25.00

R25.00

R25.00

All dimensions are in millimeters

CORE DETAIL

8234350_Reel_rev_C

Revision history STL66DN3LLH5

5 Revision history

14/15

Table 10: Document revision history

Date	Revision	Changes
12-Oct-2011	1	First release.
14-Mar-2012	2	Document status changed from preliminary data to production data. Inserted Section 5: Packaging mechanical data. Minor text changes.
28-Aug-2015	3	Text and formatting changes throughout document Updated device marking information. Updated device package information.

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